



## Advanced Product Change Notification

202102035A : GTL2014PW Conversion to Roughened Lead Frame and Wire Size Consolidation

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Jun 14, 2021

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For detailed information we invite you to view this notification online

### Management summary

GTL2014PW devices will convert to a roughened leadframe for improved package reliability. Additionally, the wire size will change to 18u diameter for material standardization which will de-risk potential delays due to material imbalances.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

## PCN Overview

### Description

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ATBK will convert GTL2014PW to a roughened leadframe for quality improvement and will consolidate wire sizes (20u, 25u) to 18u. With the use of roughened lead frames, the product data sheets will be updated and available on the NXP website showing a new orderable part number reflecting the use of Static Shielding Bags (SSB).

### Reason

The roughened leadframe offers superior delamination performance after customer SMT. Conversion to 18u de-risks potential line-downs due to material imbalances and improves manufacturing efficiencies by consolidating wire size.

### Identification of Affected Products

Product identification does not change

### Product Availability

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### Sample Information

Samples are available upon request

### Production

Planned first shipment Sep 27, 2021

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality

### **Data Sheet Revision**

A new datasheet will be issued

### **Disposition of Old Products**

Existing inventory will be shipped until depleted

## Timing and Logistics

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The Self Qualification Report will be ready on Jul 12, 2021.

The Final PCN is planned to be issued on: Aug 10, 2021.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 14, 2021.

## Contact and Support

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
GTL2014PW,118	935277499118	GTL2014PW	GTL2014	(T)SSOP14	SOT402-1	RF5	No	BLC6